

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An anisotropic conductive adhesive material, for connecting a protuberant electrode of an electronic component to a terminal electrode of a circuit board for carrying the electronic component, the anisotropic conductive adhesive material comprising at least one curable resin and silica particles, wherein:

the silica particles have a specific surface area S (m^2/g) satisfying Equation (1) below;

$$11 < S \leq 17 \quad (1);$$

the silica particles have a mean particle size D_1 (μm) and maximum particle size D_2 (μm) satisfying Equations (2) and (3) below, respectively,

$$D_1 \leq 5 \quad (2);$$

$$D_2 \leq 0.5 (h_1 + h_2) \quad (3);$$

_____ wherein h_1 represents the height of the protuberant electrode in the electronic component, and h_2 represents the height of the terminal electrode in the circuit board,

the content of the silica particles is 35 to 60 vol%, and

the mean particle size D_1 of the silica particles further satisfies the Equation (4) ~~below~~ below,

$$0.1(h_1 + h_2) \geq D_1 \quad (4);$$

_____ wherein the anisotropic conductive adhesive material further comprises conductive particles having a mean particle size of 0.5 to 8.0 μm ; and

_____ wherein the anisotropic conductive adhesive material has a coefficient of moisture absorption in a 85% RH, 85°C atmosphere is 1.5 wt % or less.

2-5. (Canceled)

6. (Previously Presented) The adhesive material according to Claim 1, wherein the electronic component is a semiconductor element.

7. (Canceled)